Attendees:
Darby DeGan
Sean Conlin
Mr. Lehman
Hamad Aldosarry
Hunter Browning

Start Time: 10:30am
End Time: 11:20am

Talking Points:
- Prototyping ideas
- Power input was good. Having overhead on that is good design
- Block diagram overall looks good and has all the fundamentals
- Where does fault detection come into the project? How will we handle faults?
- Possibly learn what all the different faults mean as we progress further into the project
- Instead of MAQ20, we could use other Dataforth modules in our design
- SLX300 system
- Just use AD modules instead of full acquisition systems
- Dataforth modules integrated inside of the design
- 2 different ways we could accomplish the goal
  - Via the MAQ20/SLX300 full acquisition systems
  - Via single modules throughout design to work with our current block diagram
- Temperature monitoring added to our design
- Could look into using RaspberryPi or Beaglebone if we are comfortable with them and they could be more useful
- How to order parts, or we can order parts and get reimbursed
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MAQ20 Qs:
- How to integrate with the MAQ20 ISOV2
  - Would duplicate what we already have for our design
  - MAQ20 connects to the battery with a voltage connector
  - Use MAQ20 ISOV to connect to the battery to monitor cell voltages that are fed to the MSP430 and go from there
  - If using MAQ20 MSP430 might not be resourced high enough for the project
  - Digitize data so it can be used for algorithm

For Next Time:
- Mr. Lehman will talk with his team to see about interfacing with MAQ20 and what MSP430 would be best to accomplish that
- Talk more about prototyping and parts that will go into prototyping
- Progress updates

Hunter's additional notes:
- Key question: How to take equipment (MSP) and interface with battery / charger using DF products?
  - How to interface and what's possible for MSP to MAQ?
    - Lehman has a firmware guy to ask for this info
    - Would determine what MSP would be needed if any
- Do we want to interface with MAQ or do the data digitizing on MSP?
- Communications from MSP to DF products can be complicated, difficult, and there are many options.
- Potential STM/AD Modules between BATTERY and TERMINAL